

**Features:**

Lower density
High breakdown voltage
Good heat spreader
High volume resistivity
Good EMC
Ideal for direct metalisation
Good thermal cycling stability

Applications:

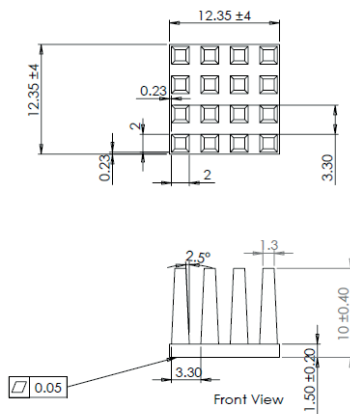
Metal heat sink replacement, LED, Chipset cooling, power modules, IC cooling

Property		Units	Value
Physical	Material	N/A	Al ₂ O ₃
	Density	g/cm ³	3.66
	Water absorption	%	0.002
	Acid resistance	mg/cm ³	≤ 0.2
	Alkali resistance	mg/cm ³	≤ 0.2
Mechanical	Mohs hardness	HV	9
	Bend Strength	MPa	≥610
	Compression Intensity	MPa	≥620
Thermal	Max. working temperature	°C	1400
	CTE, thermal expansion coefficient	(1x10 ⁻⁶) mm/ °C	7.8 - 8.3
	Thermal Conductivity	W/m K	25

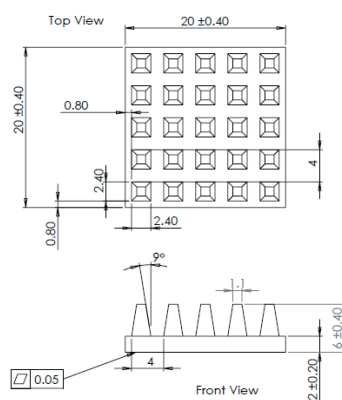
Part Number	Description Size	R _{th} (°C/W) at 100 lfm	R _{th} (°C/W) at 400 lfm	Dwg
SF-CHS-121210P #2522601	12x12x10mm pin fin spreader	37.8	18.5	A
SF-CHS-202006P #2522602	20x20x6mm pin fin heat spreader	40.0	23.7	B
SF-CHS303006P #2522604	30x30x6mm pin fin heat spreader	26.7	15.7	C
SF-CHS-323206P #2522605	32x32x6mm pin fin heat spreader	22.4	13.2	D
SF-CHS-434306P #2522606	43x43x6mm pin fin heat spreader	12.2	7.5	E
SF-CHS-606015P #2522607	60x60x15mm pin fin heat spreader	5.2	2.4	F

Drawing layouts:

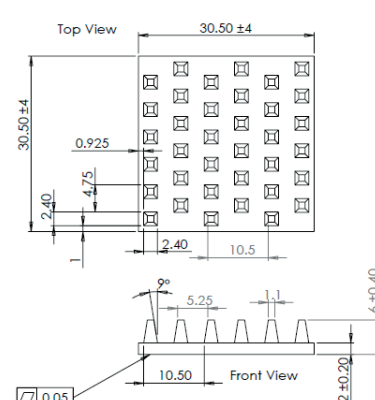
Drawing A: 12x12x10mm



Drawing B: 20x20x6mm

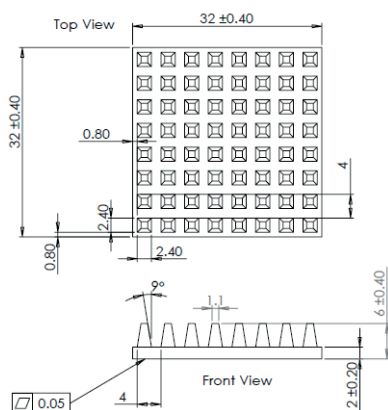


Drawing C: 30x30x6mm

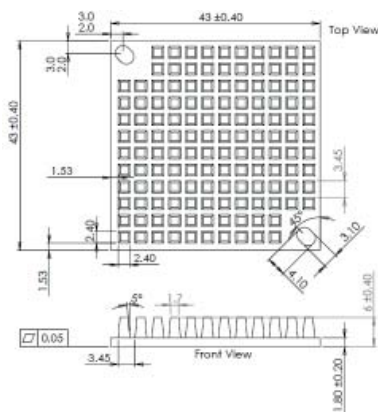


Drawing layouts:

Drawing D: 32x32x6mm



Drawing E: 43x43x6mm



Drawing F: 60x60x15mm

